

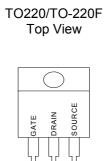
### **GENERAL DESCRIPTION**

#### This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

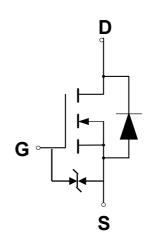
### **PIN CONFIGURATION**

### FEATURES

- Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- Diode is Characterized for Use in Bridge Circuits
- I<sub>DSS</sub> and V<sub>DS</sub>(on) Specified at Elevated Temperature
- Ciss improvement



### SYMBOL



N-Channel MOSFET

### **ABSOLUTE MAXIMUM RATINGS**

| Rating   | Symbol                            | Value      | Unit |
|--|-----------------------------------|------------|------|
| Drain to Current – Continuous  | I <sub>D</sub>                    | 13         | А    |
| - Pulsed   | I <sub>DM</sub>                   | 39         |      |
| Gate-to-Source Voltage – Continue  | V <sub>GS</sub>                   | ±30        | V    |
| Total Power Dissipation – TO220  | PD                                | 193        | W    |
| – TO220FP  |                                   | 47         |      |
| Derate above 25°C – TO220  |                                   | 1.54       | W/°C |
| – TO220FP  |                                   | 0.38       |      |
| Operating and Storage Temperature Range  | T <sub>J</sub> , T <sub>STG</sub> | -55 to 150 | °C   |
| Single Pulse Drain-to-Source Avalanche Energy $-$ T <sub>J</sub> = 25 $^{\circ}$ C | E <sub>AS</sub>                   | 605        | mJ   |
| $(V_{DD} = 100V, V_{GS} = 10V, I_L = 11A, L = 10mH, R_G = 25\Omega)$               |                                   |            |      |
| Thermal Resistance – Junction to Case -TO220                                       | θ <sub>JC</sub>                   | 0.64       | °C/W |
| <ul> <li>Junction to Case -TO220FP</li> </ul>                                      |                                   | 3.7        |      |
| <ul> <li>Junction to Ambient -TO220, TO220FP</li> </ul>                            | $\theta_{JA}$                     | 62.5       |      |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds     | TL                                | 260        | °C   |
| ESD SENSITIVITY – HBM, C=100pF, R=1.5kΩ  | Vesd                              | 2000       | V    |

### **ORDERING INFORMATION**

| Part Number       | Package |
|-------------------|---------|
| GPT13N50GN220*    | TO-220  |
| GPT13N50DGN220FP* | TO-220F |

\*Note: G : Suffix for PB Free Product

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified,  $T_J = 25^{\circ}C$ .

|   |  |                      |     | GPT13N50 | )    |       |
|---|--|----------------------|-----|----------|------|-------|
| Char  | acteristic   | Symbol               | Min | Тур      | Max  | Units |
| Drain-Source Breakdown Voltage                    |  | V <sub>(BR)DSS</sub> | 500 |          |      | V     |
| (V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA)  |  |                      |     |          |      |       |
| Drain-Source Leakage Current                      |  | I <sub>DSS</sub>     |     |          | 1    | μA    |
| $(V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V})$  |  |                      |     |          |      |       |
| Gate-Source Leakage Current-Fo                    | rward  | I <sub>GSSF</sub>    |     |          | 100  | nA    |
| $(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$  |  |                      |     |          |      |       |
| Gate-Source Leakage Current-Re                    | everse   | I <sub>GSSR</sub>    |     |          | 100  | nA    |
| $(V_{gsr} = -30 \text{ V}, V_{DS} = 0 \text{ V})$ |  |                      |     |          |      |       |
| Gate Threshold Voltage                            |  | V <sub>GS(th)</sub>  | 3   |          | 5    | V     |
| $(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$            |  |                      |     |          |      |       |
| Static Drain-Source On-Resistance                 | ce (V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.5A) *                         | R <sub>DS(on)</sub>  |     |          | 0.49 | Ω     |
| Forward Transconductance (VDS                     | = 15 V, I <sub>D</sub> = 6.5A) *   | <b>g</b> fs          |     | 8.7      |      | S     |
| Input Capacitance                                 | (V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V,                              | Ciss                 |     | 1578     |      | pF    |
| Output Capacitance                                | f = 1.0  MHz   | Coss                 |     | 180      |      | pF    |
| Reverse Transfer Capacitance                      | 1 = 1.0 Wi iz)   | C <sub>rss</sub>     |     | 9.8      |      | pF    |
| Turn-On Delay Time                                |  | t <sub>d(on)</sub>   |     | 33       |      | ns    |
| Rise Time   | (V <sub>DD</sub> = 250 V, I <sub>D</sub> = 13 A,                             | tr                   |     | 59       |      | ns    |
| Turn-Off Delay Time                               | R <sub>G</sub> = 25Ω) *  | t <sub>d(off)</sub>  |     | 75       |      | ns    |
| Fall Time   |  | t <sub>f</sub>       |     | 34.8     |      | ns    |
| Total Gate Charge                                 |  | Qg                   |     | 31       |      | nC    |
| Gate-Source Charge                                | (V <sub>DS</sub> = 400 V, I <sub>D</sub> = 13 A,<br>V <sub>GS</sub> = 10 V)* | Q <sub>gs</sub>      |     | 8.7      |      | nC    |
| Gate-Drain Charge                                 | $v_{GS} = 10 v_j$  | Q <sub>gd</sub>      |     | 12       |      | nC    |
| SOURCE-DRAIN DIODE CHARA                          | ACTERISTICS  |                      |     |          |      |       |
| Forward On-Voltage(1)                             |  | V <sub>SD</sub>      |     |          | 1.5  | V     |
| Forward Turn-On Time                              | $(I_{\rm S} = 13 \text{ A}, V_{\rm GS} = 0 \text{ V},$                       | t <sub>on</sub>      |     | **       |      | ns    |
| Reverse Recovery Time                             | $d_{IS}/d_t = 100A/\mu s)$   | t <sub>rr</sub>      |     | 450      |      | ns    |

\* Pulse Test: Pulse Width  $\leq$ 300µs, Duty Cycle  $\leq$ 2%

\*\* Negligible, Dominated by circuit inductance



### GPT13N50 / GPT13N50D

POWER FIELD EFFECT TRANSISTOR

### **TYPICAL ELECTRICAL CHARACTERISTICS**

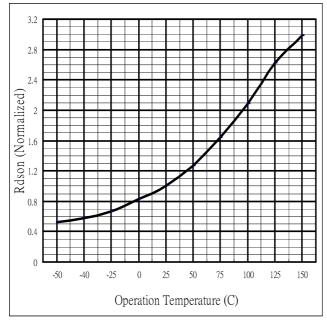


Fig 1. On-Resistance Variation with vs. Temperature

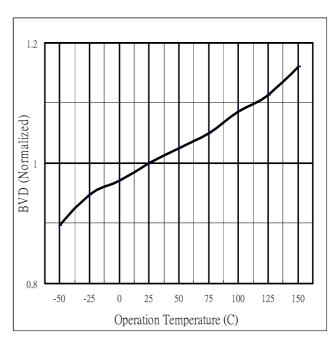


Fig.2 Breakdown Voltage Variation vs. Temperature

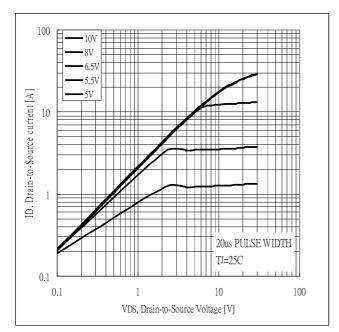


Fig 3. Typical Output Characteristics

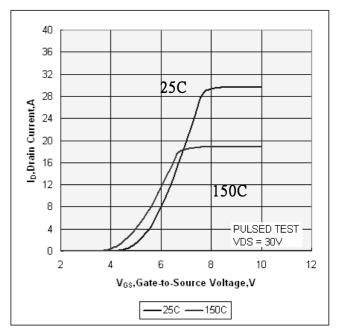


Fig 5. Typical Transfer Characteristics



### GPT13N50 / GPT13N50D

POWER FIELD EFFECT TRANSISTOR

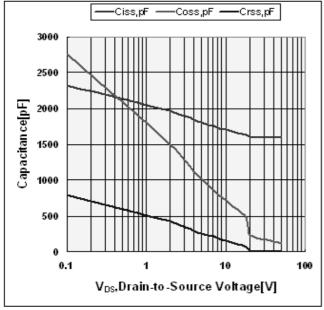


Fig 6. Typical Capacitance Vs. Gate-to-Source Voltage

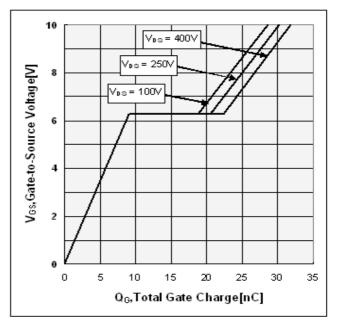


Fig 6. Typical Gate Charge Vs. Drain-to-Source Voltage

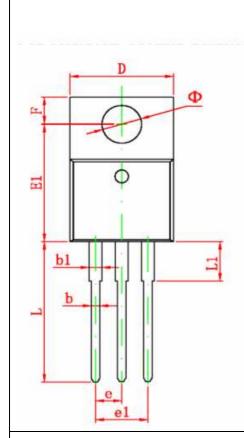
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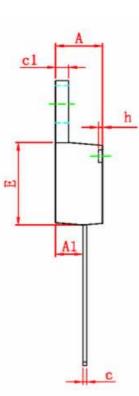
## GPT13N50 / GPT13N50D

Power Field Effect Transistor

### PACKAGE DIMENSION

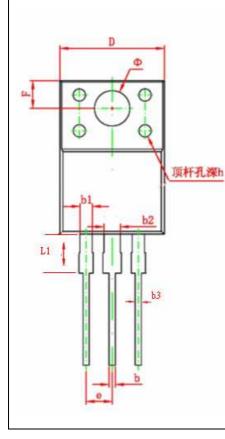
TO-220

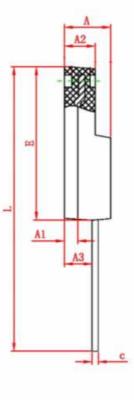




| Cause h e l | Dimensions In Millimeters |       |  |
|-------------|---------------------------|-------|--|
| Symbol      | Min.                      | Max   |  |
| А           | 4.40                      | 4.80  |  |
| A1          | 2.10                      | 2.84  |  |
| b           | 0.71                      | 0.91  |  |
| b1          | 1.17                      | 1.37  |  |
| C           | 0.30                      | 0.60  |  |
| c1          | 1.17                      | 1.47  |  |
| D           | 9.40                      | 10.60 |  |
| Е           | 8.40                      | 9.60  |  |
| е           | 2.54 TYP.                 |       |  |
| el          | 4.90                      | 5.60  |  |
| F           | 3.00                      | REF.  |  |
| Φ           | 3.50 REF.                 |       |  |
| h           | 0.00                      | 0.30  |  |
| L           | 12.50                     | 14.00 |  |
| L1          | 3.50                      | 4.00  |  |

TO-220F





| C h l  | Dimensions In Millimeters |       |  |
|--------|---------------------------|-------|--|
| Symbol | Min.                      | Max   |  |
| А      | 3.80                      | 4.70  |  |
| A1     | 1.3 REF.                  |       |  |
| A2     | 2.20                      | 3.20  |  |
| A3     | 2.10                      | 3.20  |  |
| b      | 0.30                      | 0.95  |  |
| b1     | 1.00                      | 1.75  |  |
| b2     | 1.00                      | 1.75  |  |
| b3     | 0.50                      | 0.80  |  |
| С      | 0.30                      | 0.90  |  |
| D      | 9.90                      | 10.40 |  |
| E      | 14.60                     | 16.20 |  |
| е      | 2.54 TYP.                 |       |  |
| F      | 3.00 REF.                 |       |  |
| Φ      | 3.50 REF.                 |       |  |
| h      | 0.00                      | 0.30  |  |
| L      | 28.00                     | 30.00 |  |
| L1     | 3.20                      | 3.55  |  |



### **IMPORTANT NOTICE**

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新北市汐止區新台五路一段 96 號 21F 21F., No. 96, Sec. 1, Sintai 5th Rd., Sijhih City, Taipei County 22102, Taiwan, R.O.C. TEL: +886-2-2696 3558 FAX: +886-2-2696 3559